

## SAC0100 SOLDER BAR

- Compatible with all Types of Fluxes
- Melting Point: 227°C
- Good Solderability and Spreading
- Manufactured with Automated Vacuumized Technology
- Superior Wetting Speed
- Cost effective than SAC305
- Low Dross Generation



### DESCRIPTION

PAI SAC0100 RoHS-Compliant Solder Sticks are formulated using high-purity virgin metals and processed through state-of-the-art Vacuumized Technology, ensuring exceptional product quality and consistency. The advanced manufacturing process virtually eliminates oxygen interaction with the alloy, resulting in minimal dross formation during PCB assembly. This enhances flow characteristics and significantly reduces impurity levels. PAI SAC0100 is fully compatible with a wide range of flux formulations commonly used in today's electronics industry, making it a reliable choice for high-performance lead-free soldering applications.

### HANDLING & STORAGE

| PARAMETER  | DURATION | TEMPERATURE      |
|------------|----------|------------------|
| Shelf Life | 10 years | Room Temperature |

Store the material in a dry, cool, and non-corrosive area, away from fire or open flames. Always wear appropriate Personal Protective Equipment (PPE) while handling or processing to ensure safety.

### STANDARD AVAILABILITY

SAC0100 is available in 10kgs of standard packaging.

### ALLOY COMPOSITION

| ALLOY COMPOSITION CRITERIA |                |                |                 |
|----------------------------|----------------|----------------|-----------------|
| Sn: Rem                    | Ag: 0.09%-0.2% | Ni:0.009-0.07% | Ge:0.002%-0.02% |

### APPLICATION

SAC0100 (Sn99.9 / Ag0.1 / Cu0.0) is an ideal top-up alloy for SAC0107 (Sn99.2 / Ag0.1 / Cu0.7) solder baths when copper levels are too high. It contains no copper, so it helps dilute excess copper in the bath while maintaining the silver content. This prevents copper build-up and keeps the solder within its proper working range. SAC0100 is better than pure tin, as it also restores silver levels if they begin to drop. However, if copper levels are too low, SAC0107 should be used instead to bring Cu back up. Regular analysis of the solder bath is important to ensure correct Cu and Ag levels are maintained.

### PHYSICAL CHARACTERISTICS

| PHYSICAL CHARACTERISTICS |                               |
|--------------------------|-------------------------------|
| Alloy                    | Sn-RemAg0.1Ni0.06%Ge0.01%     |
| Shape                    | Rectangular Form              |
| Density                  | 7.4g/cm <sup>3</sup>          |
| Package Form             | 25Kgs                         |
| Application              | Wave Soldering / HASL Process |
| Shelf Life               | 10 Years                      |

### SAFETY

Ensure adequate ventilation during use. Always wear appropriate personal protective equipment (PPE). Consult the Safety Data Sheet (SDS) for detailed emergency procedures. Dispose of hazardous materials only in approved containers.

For more details, please visit Our Website at [www.pai-aimsolder.com](http://www.pai-aimsolder.com) or

Write to us on [support@pai-aimsolder.com](mailto:support@pai-aimsolder.com)

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